

## N-Channel 40-V (D-S) MOSFET

| PRODUCT SUMMARY     |                                 |                                 |                       |  |  |  |
|---------------------|---------------------------------|---------------------------------|-----------------------|--|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)         | I <sub>D</sub> (A) <sup>d</sup> | Q <sub>g</sub> (Typ.) |  |  |  |
| 40                  | 0.012 at V <sub>GS</sub> = 10 V | 12                              | 15 nC                 |  |  |  |
| 40                  | 0.012 at $V_{GS}$ = 4.5 V       | 9                               | 15 110                |  |  |  |

8 D

6

5

D 7 D

D

SO-8

Top View

S 1

S 2

S 3

G

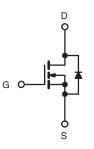
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- Halogen-free According to IEC 61249-2-21 • Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested •
- 100 % UIS Tested •
- Compliant to RoHS directive 2002/95/EC •

#### **APPLICATIONS**

- Synchronous Rectification
- POL, IBC
- Secondary Side



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATIN                               | $IGS I_A = 25 C,$                 | uniess otne     | rwise noted          |    |  |
|--|-----------------------------------|-----------------|----------------------|----|--|
| Parameter  | Symbol                            | Limit           | Unit                 |    |  |
| Drain-Source Voltage                                 |                                   | V <sub>DS</sub> | 40                   | V  |  |
| Gate-Source Voltage                                  |                                   | V <sub>GS</sub> | ± 20                 |    |  |
|  | T <sub>C</sub> = 25 °C            |                 | 12                   |    |  |
| Continuous Drain Current (T 150 °C)                  | T <sub>C</sub> = 70 °C            |                 | 8                    |    |  |
| Continuous Drain Current ( $T_J = 150 \ ^{\circ}C$ ) | T <sub>A</sub> = 25 °C            | I <sub>D</sub>  | 12.4 <sup>a, b</sup> | A  |  |
|  | T <sub>A</sub> = 70 °C            |                 | 8.8 <sup>a, b</sup>  | A  |  |
| Pulsed Drain Current                                 |                                   | I <sub>DM</sub> | 50                   |    |  |
| Avalanche Current L = 0.1 r                          |                                   | I <sub>AS</sub> | 15                   |    |  |
| Avalanche Energy                                     |                                   | E <sub>AS</sub> | 11                   | mJ |  |
|  | T <sub>C</sub> = 25 °C            | 1               | 5                    | Α  |  |
| Continuous Source-Drain Diode Current                | T <sub>A</sub> = 25 °C            | I <sub>S</sub>  | 2.1 <sup>a, b</sup>  | A  |  |
|  | T <sub>C</sub> = 25 °C            |                 | 6                    |    |  |
| Maximum Power Dissipation                            | T <sub>C</sub> = 70 °C            | Б               | 3.8                  | w  |  |
|  | T <sub>A</sub> = 25 °C            | P <sub>D</sub>  | 2.5 <sup>a, b</sup>  | vv |  |
|  | T <sub>A</sub> = 70 °C            |                 | 1.6 <sup>a, b</sup>  |    |  |
| Operating Junction and Storage Temperatur            | T <sub>J</sub> , T <sub>stq</sub> | - 55 to 150     | °C                   |    |  |

| THERMAL RESISTANCE RATINGS                  |              |                   |         |         |      |  |  |
|---|--------------|-------------------|---------|---------|------|--|--|
| Parameter                                   |              | Symbol            | Typical | Maximum | Unit |  |  |
| Maximum Junction-to-Ambient <sup>a, c</sup> | t ≤ 10 s     | R <sub>thJA</sub> | 37      | 50      | °C/W |  |  |
| Maximum Junction-to-Foot (Drain)            | Steady State | R <sub>thJF</sub> | 17      | 21      | 0/11 |  |  |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85 °C/W.

d. Based on T<sub>C</sub> = 25 °C.



| <b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted |  |   |          |       |        |       |  |
|--|--|---|----------|-------|--------|-------|--|
| Parameter  | Symbol   | Test Conditions   | Min.     | Тур.  | Max.   | Unit  |  |
| Static   |  |   |          |       |        |       |  |
| Drain-Source Breakdown Voltage                                       | V <sub>DS</sub>  | $V_{GS} = 0 V, I_D = 250 \mu A$   | 40       |       |        | V     |  |
| V <sub>DS</sub> Temperature Coefficient                              | $\Delta V_{DS}/T_{J}$  | l <sub>D</sub> = 250 μA   |          | 40    |        | mV/°C |  |
| V <sub>GS(th)</sub> Temperature Coefficient                          | $\Delta V_{GS(th)}/T_J$  |   |          | - 6   |        |       |  |
| Gate-Source Threshold Voltage  | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$   | 1        |       | 3      | V     |  |
| Gate-Source Leakage  | I <sub>GSS</sub>   | $V_{DS} = 0 V, V_{GS} = \pm 20 V$   |          |       | ± 100  | nA    |  |
| Zero Gate Voltage Drain Current                                      | I <sub>DSS</sub>   | $V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$<br>$V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$ |          |       | 1<br>5 | μA    |  |
| On-State Drain Current <sup>a</sup>                                  | I <sub>D(on)</sub>   | $V_{DS} \ge 5 V, V_{GS} = 10 V$   | 50       |       |        | A     |  |
|  |  | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 12.4 \text{ A}$   |          | 0.010 |        | Ω     |  |
| Drain-Source On-State Resistance <sup>a</sup>                        | R <sub>DS(on)</sub>  | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10.8 \text{ A}$  |          | 0.012 |        |       |  |
| Forward Transconductance <sup>a</sup>                                | 9 <sub>fs</sub>  | $V_{\rm DS} = 15 \text{ V}, \text{ I}_{\rm D} = 12.4 \text{ A}$   |          | 56    |        | S     |  |
| Dynamic <sup>b</sup>   |  | 1   | L        |       |        |       |  |
| Input Capacitance  | C <sub>iss</sub>   |   |          | 2000  |        | pF    |  |
| Output Capacitance   | C <sub>oss</sub>   | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz  |          | 260   |        |       |  |
| Reverse Transfer Capacitance   | C <sub>rss</sub>   |   |          | 150   |        |       |  |
|  | $Q_g = \frac{V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_D = 12.4 \text{ A}}{V_{DS} = 10 \text{ V}, \text{ I}_D = 12.4 \text{ A}}$ | $V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 12.4 \text{ A}$  |          | 33    | 50     | nC    |  |
| Total Gate Charge  |  |   |          | 15    | 23     |       |  |
| Gate-Source Charge   | Q <sub>gs</sub>  | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 12.4 A  |          | 6.7   |        |       |  |
| Gate-Drain Charge  | Q <sub>gd</sub>  |   |          | 5.1   |        |       |  |
| Gate Resistance  | R <sub>g</sub>   | f = 1 MHz   |          | 1.4   | 2.1    | Ω     |  |
| Turn-On Delay Time   | t <sub>d(on)</sub>   |   |          | 25    | 40     | -     |  |
| Rise Time  | t <sub>r</sub>   | $V_{DD}$ = 20 V, $R_{L}$ = 2 $\Omega$   |          | 12    | 20     |       |  |
| Turn-Off Delay Time  | t <sub>d(off)</sub>  | $I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, \text{ R}_g = 1 \Omega$   |          | 25    | 40     |       |  |
| Fall Time  | t <sub>f</sub>   |   |          | 10    | 15     |       |  |
| Turn-On Delay Time   | t <sub>d(on)</sub>   |   |          | 10    | 15     | ns    |  |
| Rise Time  | t <sub>r</sub>   | $V_{DD}$ = 20 V, $R_{L}$ = 2 $\Omega$   |          | 15    | 25     | -     |  |
| Turn-Off Delay Time  | t <sub>d(off)</sub>  | $I_D \cong 10 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$  |          | 30    | 45     |       |  |
| Fall Time  | t <sub>f</sub>   |   |          | 10    | 15     |       |  |
| Drain-Source Body Diode Characteristi                                | cs   |   | <u> </u> | 1     | 1      |       |  |
| Continuous Source-Drain Diode Current                                | ۱ <sub>S</sub>   | T <sub>C</sub> = 25 °C  |          |       | 30     | ^     |  |
| Pulse Diode Forward Current  | I <sub>SM</sub>  |   |          |       | 50     | A     |  |
| Body Diode Voltage   | V <sub>SD</sub>  | I <sub>S</sub> = 10 A, V <sub>GS</sub> = 0 V  |          | 0.8   | 1.2    | V     |  |
| Body Diode Reverse Recovery Time                                     | t <sub>rr</sub>  |   |          | 30    | 60     | ns    |  |
| Body Diode Reverse Recovery Charge                                   | Q <sub>rr</sub>  | $1 = 10.0 \text{ d}/\text{d} = 100.0 \text{ d}/\text{c} =05 ^{\circ}\text{C}$   |          | 26    | 52     | nC    |  |
| Reverse Recovery Fall Time   | ta   | I <sub>F</sub> = 10 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C   |          | 17.5  |        | ns    |  |
| Reverse Recovery Rise Time   | t <sub>b</sub>   | 1   |          | 12.5  |        |       |  |

emi

Notes:

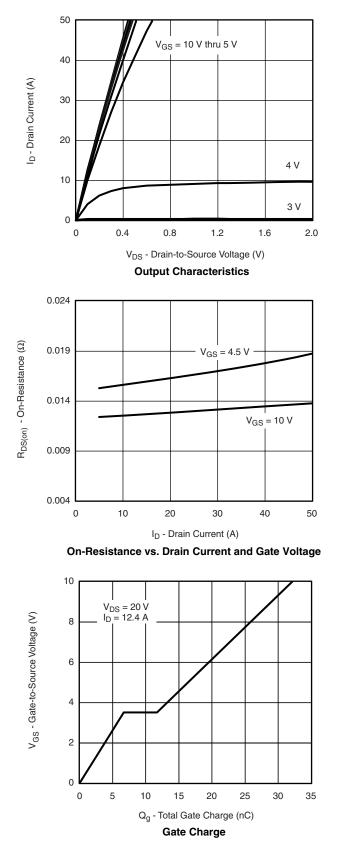
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %

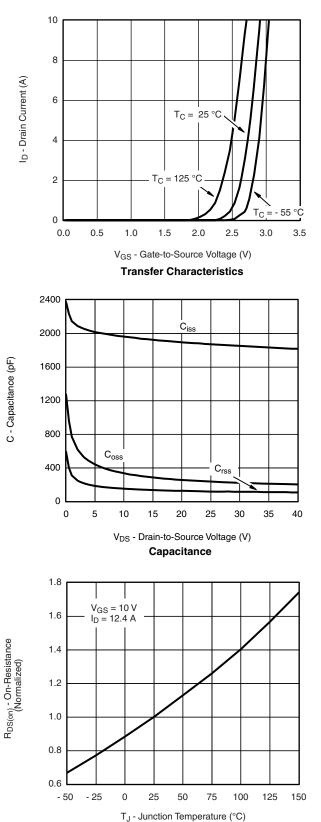
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





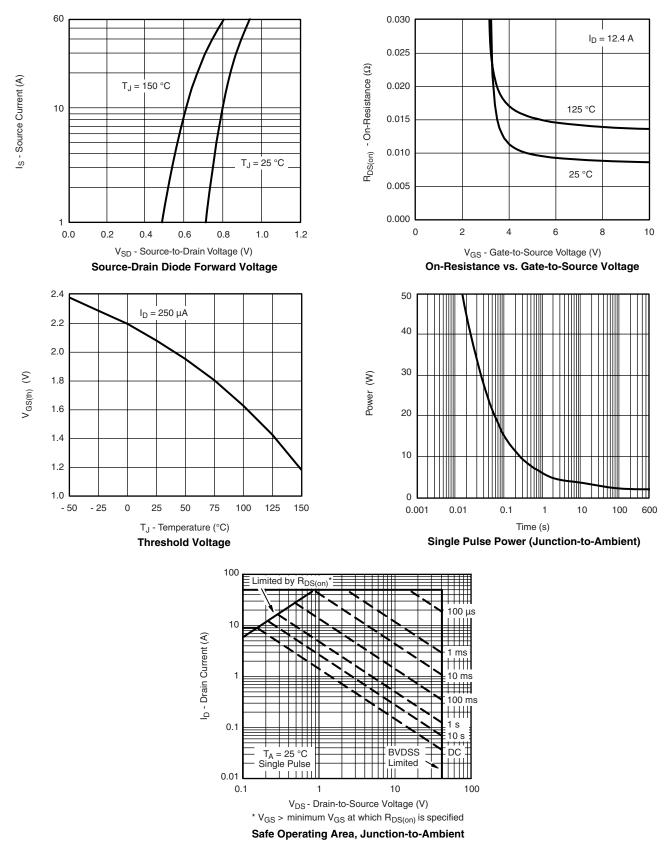




**On-Resistance vs. Junction Temperature** 

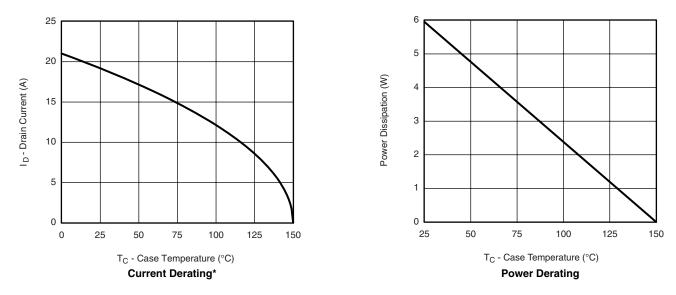


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

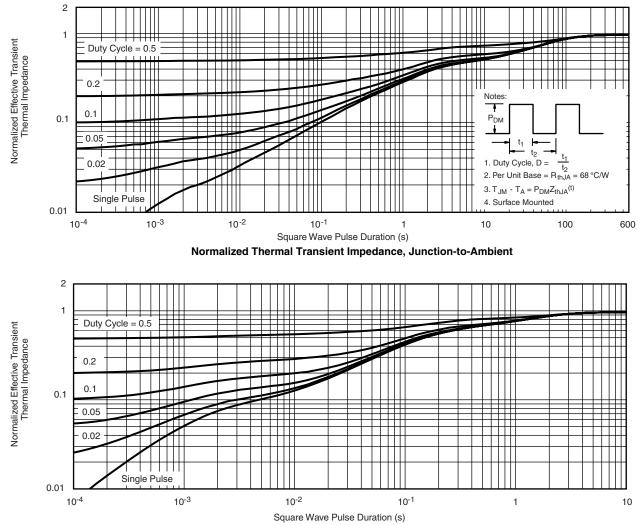




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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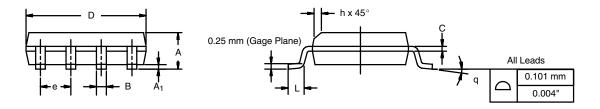
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

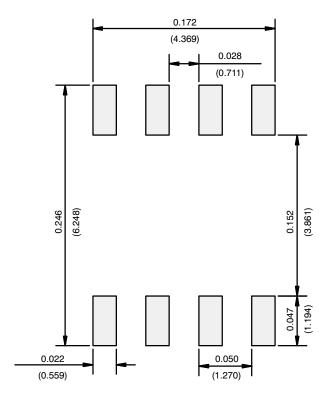




|   | MILLIM | IETERS | INCHES    |       |  |
|---|--------|--------|-----------|-------|--|
| DIM   | Min    | Max    | Min       | Max   |  |
| A   | 1.35   | 1.75   | 0.053     | 0.069 |  |
| A <sub>1</sub>                              | 0.10   | 0.20   | 0.004     | 0.008 |  |
| В   | 0.35   | 0.51   | 0.014     | 0.020 |  |
| С   | 0.19   | 0.25   | 0.0075    | 0.010 |  |
| D   | 4.80   | 5.00   | 0.189     | 0.196 |  |
| E   | 3.80   | 4.00   | 0.150     | 0.157 |  |
| е   | 1.27   | BSC    | 0.050 BSC |       |  |
| н   | 5.80   | 6.20   | 0.228     | 0.244 |  |
| h   | 0.25   | 0.50   | 0.010     | 0.020 |  |
| L   | 0.50   | 0.93   | 0.020     | 0.037 |  |
| q   | 0°     | 8°     | 0°        | 8°    |  |
| S   | 0.44   | 0.64   | 0.018     | 0.026 |  |
| ECN: C-06527-Rev. I, 11-Sep-06<br>DWG: 5498 |        |        |           |       |  |



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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